CLAIMS

What is claimed is:

1. A ~~chip scale structure comprising~~:

a semiconductor wafer with a pattern of bond pads on the surface of the semiconductor wafer;

a glass sheet with holes in a pattern matching the pattern of bond pads on the surface of the semiconductor wafer; and

a layer of adhesive adhering the glass sheet to the semiconductor wafer wherein the pattern of holes in the glass sheet are over the pattern of bond pads on the surface of the semiconductor wafer.

2. The chip scale structure of Claim 1 further comprising a metallized pad formed on the glass sheet adjacent to each hole in the glass sheet.

3. The chip scale structure of Claim 2 further comprising a conductive trace connecting each metallized pad on the glass sheet to a corresponding bond pad on the surface of the semiconductor wafer under the hole adjacent to the metallized pad on the glass sheet.

4. The chip scale structure of Claim 3 further comprising a solder ball formed

5. The chip scale structure of Claim 1 further comprising a metallized pad formed on the glass sheet adjacent to each hole in the glass sheet wherein the metallized pad extends down sides of the hole adjacent to the metallized pad.

6. The chip scale structure of Claim 5 further comprising a metal plug formed in each hole connecting the metallized pad on the sides of each hole to the bond pad under each hole.

7. The chip scale structure of Claim 5 further comprising a solder ball formed on each metallized pad on the glass sheet.

8. A method of forming a chip scale structure, the method comprising:

forming a pattern of holes in a glass sheet wherein the pattern of holes in the glass sheet matches a pattern of bond pads on a surface of a semiconductor wafer; and

adhering the glass sheet to the semiconductor die wherein the pattern of holes in the glass sheet are over the pattern of bond pads on the semiconductor wafer.

9. The method of Claim 8 further comprising forming a metallized pad on the surface of the glass sheet adjacent to each hole in the glass sheet.

10. The method of Claim 9 further comprising forming a conductive trace connecting each metallized pad on the glass sheet to the bond pad on the surface of the semiconductor wafer under the hole adjacent to the metallized pad on the glass sheet.

11. The method of Claim 10 further comprising forming a solder ball formed on each metallized pad on the glass sheet.

12. The method of Claim 8 further comprising forming a metallized pad on the glass sheet adjacent to each hole in the glass sheet wherein the metallized pad extends down sides of the hole adjacent to the metallized pad.

13. The method of Claim 12 further comprising forming a metal plug formed in each hole connecting the metallized pad on the sides of each hole to the bond pad under each hole.

14. The method of Claim 13 further comprising forming a solder ball on each metallized pad on the glass sheet.